SLLS085B - JANUARY 1977 - REVISED MAY 1995

- Meets or Exceeds the Requirements of ANSI EIA/TIA-422-B and ITU Recommendation V.11
- Single 5-V Supply
- Balanced-Line Operation
- TTL Compatible
- High Output Impedance in Power-Off Condition
- High-Current Active-Pullup Outputs
- Short-Circuit Protection
- Dual Channels
- Input Clamp Diodes

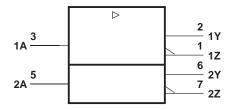
† The PS package is only available left-end taped and reeled, i.e., order SN75158PSLE.

description

The SN75158 is a dual differential line driver designed to satisfy the requirements set by the ANSI EIA/TIA-422-B and ITU V.11 interface specifications. The outputs provide complementary signals with high-current capability for driving balanced lines, such as twisted pair, at normal line impedance without high power dissipation. The output stages are TTL totem-pole outputs providing a high-impedance state in the power-off condition.

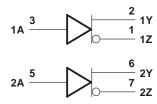
The SN75158 is characterized for operation from 0°C to 70°C.

logic symbol‡



[‡] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)

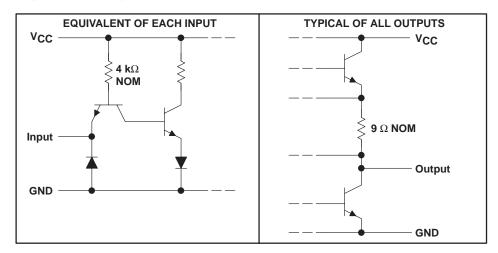




Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| Supply voltage, V _{CC} (see Note 1) | |
|--|------------------------------|
| Input voltage, V _I | 5.5 V |
| Continuous total power dissipation | See Dissipation Rating Table |
| Operating free-air temperature range, T _A | 0°C to 70°C |
| Storage temperature range, T _{stg} | 65°C to 150°C |
| Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds | 260°C |

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values, except differential output voltage VOD, are with respect to network ground terminal. VOD is at the Youtput with respect to the Z output.

DISSIPATION RATING TABLE

| PACKAGE | $\begin{aligned} & \textbf{T}_{\pmb{A}} \leq \textbf{25}^{\circ}\textbf{C} \\ & \textbf{POWER RATING} \end{aligned}$ | DERATING FACTOR ABOVE T _A = 25°C | T _A = 70°C POWER RATING |
|---------|--|--|---------------------------------------|
| D | 725 mW | 5.8 mW/°C | 464 mW |
| Р | 1000 mW | 8.0 mW/°C | 640 mW |
| PS | 450 mW | 3.6 mW/°C | 288 mW |

recommended operating conditions

| | MIN | NOM | MAX | UNIT |
|--|------|-----|------|------|
| Supply voltage, V _{CC} | 4.75 | 5 | 5.25 | V |
| High-level input voltage, V _{IH} | 2 | | | V |
| Low-level input voltage, V _{IL} | | | 0.8 | V |
| High-level output current, I _{OH} | | | -40 | mA |
| Low-level output current, I _{OL} | | | 40 | mA |
| Operating free-air temperature, T _A | 0 | | 70 | °C |



SLLS085B - JANUARY 1977 - REVISED MAY 1995

electrical characteristics over operating free-air temperature range (unless otherwise noted)

| | PARAMETER | TEST C | ONDITIONS† | MIN | TYP‡ | MAX | UNIT |
|---------------------|---|--|--|-----|-------|--------------------|------|
| VIK | Input clamp voltage | V _{CC} = MIN, | I _I = -12 mA | | -0.9 | -1.5 | V |
| Vон | High-level output voltage | V _{CC} = MIN, V _{IH} = 2 V, | $V_{IL} = 0.8 \text{ V},$ $I_{OH} = -40 \text{ mA}$ | 2.4 | 3 | | ٧ |
| VOL | Low-level output voltage | V _{CC} = MIN, V _{IH} = 2 V, | $V_{IL} = 0.8 \text{ V},$ $I_{OL} = 40 \text{ mA}$ | | 0.2 | 0.4 | V |
| V _{OD1} | Differential output voltage | $V_{CC} = MAX$, | IO = 0 | | 3.5 | 2×V _{OD2} | V |
| IV _{OD2} I | Differential output voltage | $V_{CC} = MIN$ | | 2 | 3 | | V |
| ΔV_{OD} | Change in magnitude of differential output voltage§ | $V_{CC} = MIN$ |] | | ±0.02 | ±0.4 | V |
| \/ | | $V_{CC} = MAX$ | $R_L = 100 \Omega$, | | 1.8 | 3 | V |
| Voc | Common-mode output voltage¶ | V _{CC} = MIN | See Figure 1 | | 1.5 | 3 | V |
| ΔVOC | Change in magnitude of common-mode output voltage§ | V _{CC} = MIN or MAX | | | ±0.02 | ±0.4 | V |
| | | | V _O = 6 V | | 0.1 | 100 | |
| l _O | Output current with power off | $V_{CC} = 0$ | $V_0 = -0.25 \text{ V}$ | | -0.1 | -100 | μΑ |
| | | | $V_0 = -0.25 \text{ to } 6 \text{ V}$ | | | ±100 | |
| Ц | Input current at maximum input voltage | $V_{CC} = MAX$, | V _I = 5.5 V | | | 1 | mA |
| lн | High-level input current | $V_{CC} = MAX$, | V _I = 2.4 V | | | 40 | μА |
| I _I L | Low-level input current | $V_{CC} = MAX$, | V _I = 0.4 V | | -1 | -1.6 | mA |
| los | Short-circuit output current# | $V_{CC} = MAX$ | | -40 | -90 | -150 | mA |
| ICC | Supply current (both drivers) | $V_{CC} = MAX,$ $T_A = 25^{\circ}C,$ | Inputs grounded, No load | | 37 | 50 | mA |

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

| | PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|------------------|--|----------------------------------|-----|-----|-----|------|
| ^t PLH | Propagation delay time, low-to-high-level output | See Figure 2, Termination A | | 16 | 25 | ns |
| ^t PHL | Propagation delay time, high-to-low-level output | See Figure 2, Terrilliation A | | 10 | 20 | ns |
| ^t PLH | Propagation delay time, low-to-high-level output | See Figure 2, Termination B | | 13 | 20 | ns |
| tPHL | Propagation delay time, high-to-low-level output | See Figure 2, Termination B | | 9 | 15 | ns |
| tTLH | Transition time, low-to-high-level output | Con Figure 2. Termination A | | 4 | 20 | ns |
| tTLH | Transition time, high-to-low-level output | See Figure 2, Termination A 4 20 | | 20 | ns | |
| | Overshoot factor | See Figure 2, Termination C | | | 10% | |

[‡] All typical values are at V_{CC} = 5 V and T_A = 25°C except for V_{OC} , for which V_{CC} is as stated under test conditions. ΔV_{OD} and $\Delta |V_{OC}|$ are the changes in magnitudes of V_{OD} and V_{OC} , respectively, that occur when the input is changed from a high level to a low

[¶] In ANSI Standard EIA/TIA-422-B, VOC, which is the average of the two output voltages with respect to ground, is called output offset voltage, Vos.

[#]Only one output should be shorted at a time, and duration of the short circuit should not exceed one second.

PARAMETER MEASUREMENT INFORMATION

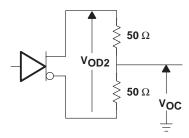
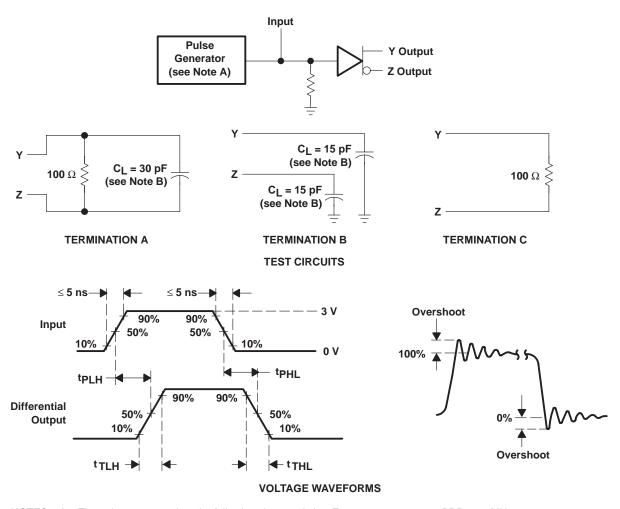


Figure 1. Differential and Common-Mode Output Voltages



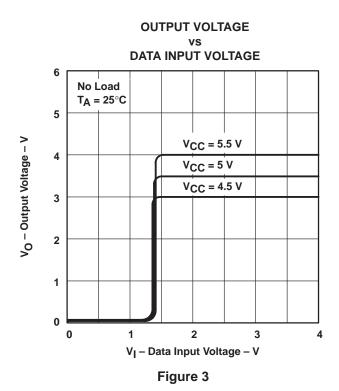
NOTES: A. The pulse generator has the following characteristics: Z_O = 50 Ω , t_W = 25 ns, PRR \leq 10 MHz.

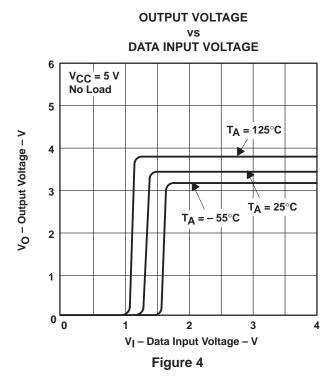
B. C_I includes probe and jig capacitance.

Figure 2. Test Circuit and Voltage Waveforms

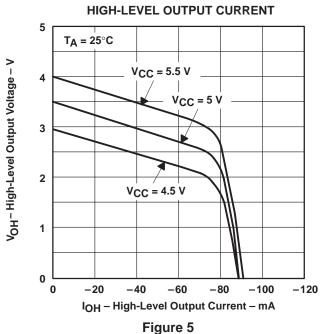


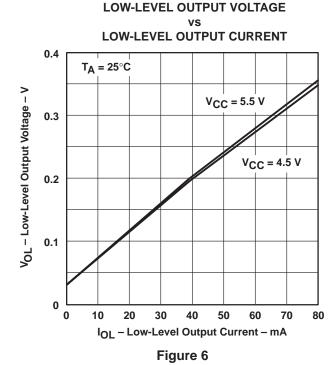
TYPICAL CHARACTERISTICS



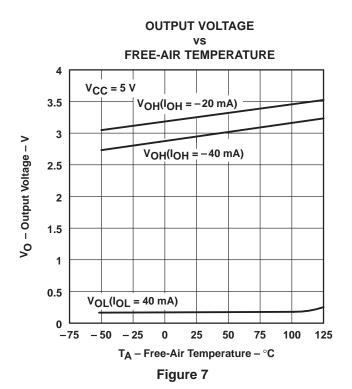


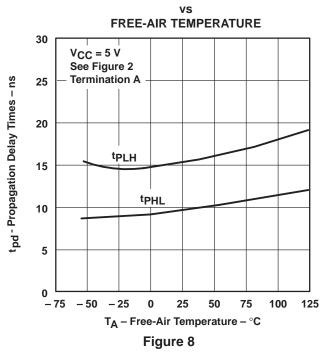




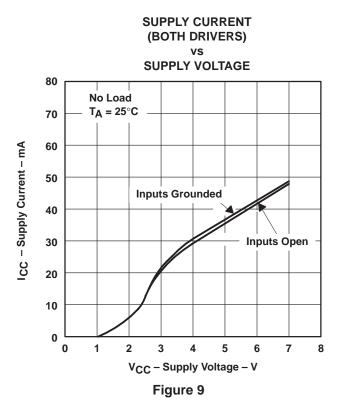


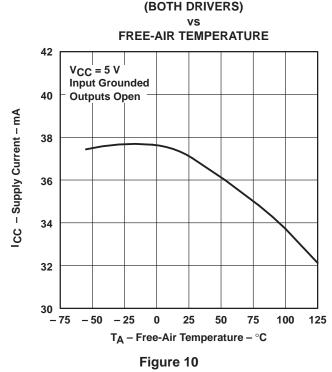
TYPICAL CHARACTERISTICS





PROPAGATION DELAY TIMES





SUPPLY CURRENT

TYPICAL CHARACTERISTICS

SUPPLY CURRENT (BOTH DRIVERS)

FREQUENCY

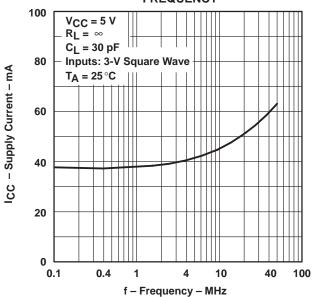


Figure 11

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

| | Applications | |
|------------------------|---|---|
| amplifier.ti.com | Audio | www.ti.com/audio |
| dataconverter.ti.com | Automotive | www.ti.com/automotive |
| dsp.ti.com | Broadband | www.ti.com/broadband |
| interface.ti.com | Digital Control | www.ti.com/digitalcontrol |
| logic.ti.com | Military | www.ti.com/military |
| power.ti.com | Optical Networking | www.ti.com/opticalnetwork |
| microcontroller.ti.com | Security | www.ti.com/security |
| www.ti.com/lpw | Telephony | www.ti.com/telephony |
| | Video & Imaging | www.ti.com/video |
| | Wireless | www.ti.com/wireless |
| | dataconverter.ti.com dsp.ti.com interface.ti.com logic.ti.com power.ti.com microcontroller.ti.com | amplifier.ti.com dataconverter.ti.com dsp.ti.com dsp.ti.com interface.ti.com logic.ti.com power.ti.com microcontroller.ti.com www.ti.com/lpw Audio Audio Audio Audio Automotive Broadband Digital Control Military Optical Networking Security Telephony Video & Imaging |

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2007, Texas Instruments Incorporated







PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | e Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|-----------------|--------------------|------|----------------|---------------------------|------------------|------------------------------|
| SN75158D | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN75158DE4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN75158DG4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN75158DR | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN75158DRE4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN75158DRG4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN75158P | ACTIVE | PDIP | Р | 8 | 50 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN75158PE4 | ACTIVE | PDIP | Р | 8 | 50 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type |
| SN75158PSLE | OBSOLETE | SO | PS | 8 | | TBD | Call TI | Call TI |
| SN75158PSR | ACTIVE | SO | PS | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN75158PSRE4 | ACTIVE | SO | PS | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN75158PSRG4 | ACTIVE | SO | PS | 8 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.



PACKAGE OPTION ADDENDUM

18-Sep-2008

| · · · · · · · · · · · · · · · · · · · |
|--|
| no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by Customer on an annual basis. |
| |
| |
| |
| |
| |
| |
| |
| |
| |
| |
| |
| |
| |
| |
| |
| |
| |
| |



TAPE AND REEL INFORMATION





| | Dimension designed to accommodate the component width |
|----|---|
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | | | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------|-----------------|--------------------|---|------|--------------------------|--------------------------|---------|---------|---------|------------|-----------|------------------|
| SN75158DR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| SN75158PSR | SO | PS | 8 | 2000 | 330.0 | 16.4 | 8.2 | 6.6 | 2.5 | 12.0 | 16.0 | Q1 |





*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN75158DR | SOIC | D | 8 | 2500 | 340.5 | 338.1 | 20.6 |
| SN75158PSR | SO | PS | 8 | 2000 | 346.0 | 346.0 | 33.0 |

D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AA.





NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001

For the latest package information, go to http://www.ti.com/sc/docs/package/pkg_info.htm

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products Amplifiers amplifier.ti.com Data Converters dataconverter.ti.com DSP dsp.ti.com Clocks and Timers www.ti.com/clocks Interface interface.ti.com Logic logic.ti.com Power Mgmt power.ti.com Microcontrollers microcontroller.ti.com www.ti-rfid.com RF/IF and ZigBee® Solutions www.ti.com/lprf

| Applications | |
|--------------------|---------------------------|
| Audio | www.ti.com/audio |
| Automotive | www.ti.com/automotive |
| Broadband | www.ti.com/broadband |
| Digital Control | www.ti.com/digitalcontrol |
| Medical | www.ti.com/medical |
| Military | www.ti.com/military |
| Optical Networking | www.ti.com/opticalnetwork |
| Security | www.ti.com/security |
| Telephony | www.ti.com/telephony |
| Video & Imaging | www.ti.com/video |
| Wireless | www.ti.com/wireless |

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2008, Texas Instruments Incorporated